High Voltage LED Series Chip on Board

LCo40D-Gen.1

High efficacy COB LED package well-suited for use in spotlight applications

Features & Benefits

- Chip on Board (COB) solution makes it easy to design in •
- Simple assembly reduces manufacturing cost •
- Low thermal resistance •
- InGaN/GaN MQW LED with long time reliability •

Applications

- Spotlight / Downlight •
- LED Retrofit Bulbs
- Outdoor Illumination •





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1. Characteristics

a) Absolute Maximum Rating

ltem	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +105	٥C	-
Storage Temperature	T _{stg}	-40 ~ +120	٥C	-
LED Junction Temperature	TJ	140	٥C	-
Case Temperature	Тс	105	٥C	
Forward Current	l _F	2760	mA	-
Power Dissipation	P _D	103.5	W	-
ESD (HBM)	-	±2	kV	-
ESD (MM)	-	±0.5	kV	-

b) Electro-optical Characteristics $(I_F = 1080 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C})$

Item	Unit	Rank	Min.	Тур.	Max.
Forward Voltage (V _F)	V	YZ	31.8	34.6	37.5
Color Decidering Jadey (D.)		5	80	-	-
Color Rendering Index (R _a)	-	7	90		
Thermal Resistance (junction to chip point)	°C/W		-	0.8	-
Beam Angle	0		-	115	-
Nominal Power	W			40.5	

Notes:

- 1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature ($T_J = T_C = T_a = 85 \text{ °C}$)
- 2) Samsung maintains measurement tolerance of: forward voltage = \pm 5 %, CRI = \pm 1
- 3) Refer to the derating curve, '3. Typical Characteristics Graph' designed within the range.

c) Luminous Flux Characteristics (I_F = 1080 mA)

CRI (R _a)	Nominal	Flux	Flux @ T _J = 85 °C (lm)			
Min.	CCT (K)	Rank	Min.	Тур.	Max.	
	2700	M7	4746	4996	-	
	2700 "	D1	4996	5246	-	
	2000	M9	4994	5257	-	
	3000	D1	5257	5520	-	
	3500	N1	5147	5418	-	
		D1	5418	5689	-	
80	4000	N2	5258	5535	-	
00	4000	D1	5535	5812	-	
	5000	N2	5283	5561	-	
	5000	D1	5561	5839	-	
	5700	N3	5309	5588	-	
	5700	D1	5588	5868	-	
	6500	N2	5251	5528	-	
	6500	D1	5528	5804	-	

Nominal	Flux	Flux @ T」 = 85 °C (lm)			
CCT (K)	Rank	Min.	Тур.	Max.	
2700	MO	4068	4283	-	
2700	D1	4283	4497	-	
3000	M2	4298	4525	-	
	D1	4525	4751	-	
	M4	4408	4640	-	
3500	D1	4640	4872	-	
4000	M5	4505	4742	-	
4000	D1	4742	4979	-	
5000	M5	4556	4796	-	
	D1	4796	5036	-	
	ССТ (К) 2700 · 3000 · 3500 · 4000 ·	$ \begin{array}{c} CCT (K) & Rank \\ \hline 2700 & \hline \\ 2700 & D1 \\ 3000 & D1 \\ 3000 & D1 \\ 3500 & D1 \\ 4000 & D1 \\ 4000 & D1 \\ 5000 & M5 \\ 5000 & \hline \\ 5000 & \hline \\ \\ \\ $	$ \begin{array}{c ccr} CCT (k) & Rank & Min. \\ M0 & 4068 \\ 2700 & D1 & 4283 \\ 3000 & D1 & 4298 \\ 3000 & D1 & 4525 \\ 3500 & D1 & 4525 \\ 4525 & M4 & 4408 \\ 3500 & D1 & 4640 \\ 4000 & M5 & 4505 \\ 4000 & D1 & 4742 \\ 4000 & D1 & 4742 \\ 4556 & 5000 & M5 & 4556 \\ 5000 & M5 & M5 & 4556 \\ 5000 & M5 & M5 & M5 \\ 5000 & M5 & M5 \\ 500 & M5 & M5 \\ 500 & M$	$ \begin{array}{c cccc} $	

Notes:

- 1) The COB is tested in pulsed operating condition at rated test current (10 ms pulse width) and rated temperature ($T_J = T_C = 85 \text{ °C}$).
- 2) Samsung maintains measurement tolerance of: Luminous flux = \pm 7 %, CRI = \pm 1

2. Product Code Information

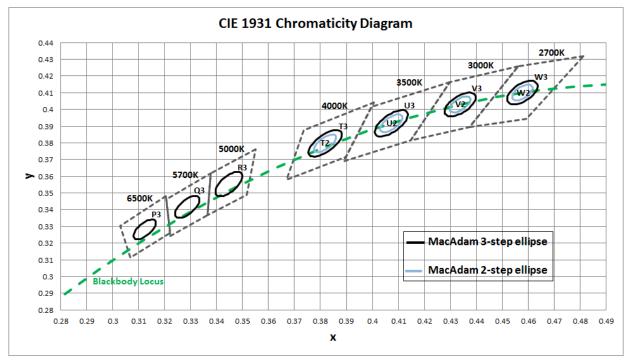
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S																	

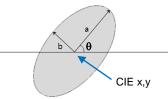
Digit	PKG Information	Code	Specification
1 2 3	Samsung Package High Power	SPH	
4 5	Color	WH	White
6	Product Version	Α	
7 8	Form Factor	HD	СОВ
9	Lens Type	N	No lens
10	Wattage or Model	к	LC040D
11	Internal Code	2	
12	CRI & Sorting Temperature	5 7	Min. 80 (85°C) Min. 90 (85°C)
13 14	Forward Voltage (V)	YZ	31.8~37.5
15	CCT (K)	W V U T R Q P	2700K 3000K 3500K 4000K 5000K 5700K 6500K
16	MacAdam Step	2 3	MacAdam 2-step MacAdam 3-step
17 18	Luminous Flux	M0 M2 M4 M5 M7 M9 N1 N2 N3 D1	Min. 4000 Min. 4200 Min. 4400 Min. 4500 Min. 4700 Min. 4700 Min. 5100 Min. 5200 Min. 5300 Add rank

a) Binning Structure $(I_F = 1080 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C})$

CRI (R₃) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _v , Im)
		SPHWHAHDNK25YZW2M7		W2	147	4740
		SPHWHAHDNK25YZW3M7	··· YZ	W3	M7	4746 ~
	2700 "	SPHWHAHDNK25YZW2D1		W2	D1	4996 ~
		SPHWHAHDNK25YZW3D1		W3		4390 ~
		SPHWHAHDNK25YZV2M9		V2	M9	4994 ~
	3000	SPHWHAHDNK25YZV3M9	- YZ	V3	1019	
	3000	SPHWHAHDNK25YZV2D1		V2	D1	5257 ~
		SPHWHAHDNK25YZV3D1		V3		5257 ~
		SPHWHAHDNK25YZU2N1		U2	N1	5147 ~
	3500	SPHWHAHDNK25YZU3N1	YZ	U3		5147 ~
80		SPHWHAHDNK25YZU2D1		U2	D1	5418 ~
00		SPHWHAHDNK25YZU3D1		U3		
		SPHWHAHDNK25YZT2N2	- YZ	T2	N2	5258 ~
	4000	SPHWHAHDNK25YZT3N2		Т3	112	0200 -
	-1000	SPHWHAHDNK25YZT2D1		T2	D1	5535 ~
		SPHWHAHDNK25YZT3D1		Т3		
	5000 ···	SPHWHAHDNK25YZR3N2	- YZ	R3	N2	5283 ~
		SPHWHAHDNK25YZR3D1			D1	5561 ~
	5700	SPHWHAHDNK25YZQ3N3	YZ	Q3	N3	5309 ~
		SPHWHAHDNK25YZQ3D1		40	D1	5588 ~
	6500 ···	SPHWHAHDNK25YZP3N2	YZ	P3	N2	5251 ~
	0000	SPHWHAHDNK25YZP3D1	I Z	гJ	D1	5528 ~

CRI (R₃) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _v , Im)
		SPHWHAHDNK27YZW2M0		W2	Mo	4000
	0700	SPHWHAHDNK27YZW3M0		W3		4068 ~
	2700	SPHWHAHDNK27YZW2D1	YZ	W2	54	1000
		SPHWHAHDNK27YZW3D1		W3		4283 ~
		SPHWHAHDNK27YZV2M2		V2		
	0000	SPHWHAHDNK27YZV3M2		V3		4298 ~
	3000	SPHWHAHDNK27YZV2D1	YZ	V2		4505
		SPHWHAHDNK27YZV3D1		V3	D1	4525 ~
22		SPHWHAHDNK27YZU2M4	· YZ	U2		4400
90	0500	SPHWHAHDNK27YZU3M4		U3		4408 ~
	3500	SPHWHAHDNK27YZU2D1		U2	54	
		SPHWHAHDNK27YZU3D1		U3	D1	4640 ~
		SPHWHAHDNK27YZT2M5		T2		4505
	1000	SPHWHAHDNK27YZT3M5		Т3	. М5	4505 ~
	4000	SPHWHAHDNK27YZT2D1	YZ	T2	Di	4740
		SPHWHAHDNK27YZT3D1		Т3	- D1	4742 ~
	5000	SPHWHAHDNK27YZR3M5	V7	R3	M5	4556 ~
	5000	SPHWHAHDNK27YZR3D1	YZ	R3	D1	4796 ~





MacAdam Ellipse (W2, W3)										
Step										
2-step	0.4578	0.4101	53.70	0.0054	0.0028					
3-step	0.4578	0.4101	53.70	0.0081	0.0042					

MacAdam Ellipse (U2, U3)									
Step	CIE x	CIE y							
2-step	0.4073	0.3917	54.00	0.0062	0.0028				
3-step	0.4073	0.3917	54.00	0.0093	0.0041				

MacAdam Ellipse (R3)										
Step CIE x CIE y θ a b										
3-step 0.3447 0.3553 59.62 0.0082 0.0035										

MacAdam Ellipse (P3)							
Step CIE x		CIE y					
3-step	0.3123	0.3282	58.5700	0.0067	0.0029		

MacAdam Ellipse (V2, V3) Step CIE x CIE y θ a b 2-step 0.4338 0.403 53.22 0.0056 0.0027 3-step 0.4338 0.4030 53.22 0.0083 0.0041

MacAdam Ellipse (T2, T3)						
Step	CIE x	CIE y				
2-step	0.3818	0.3797	53.72	0.0063	0.0027	
3-step	0.3818	0.3797	53.72	0.0094	0.0040	

MacAdam Ellipse (Q3)							
Step CIE x		CIE y					
3-step	0.3287	0.3417	59.0950	0.0075	0.0032		

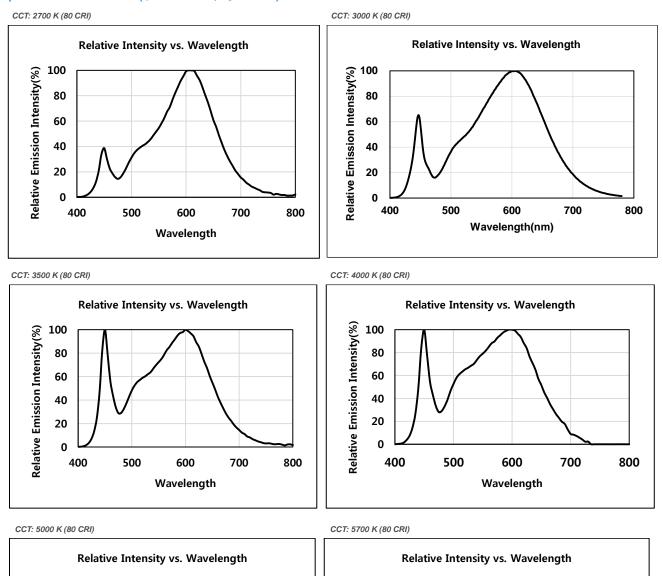
Note:

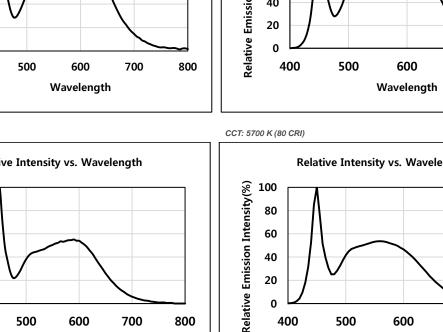
Samsung maintains measurement tolerance of: $Cx, Cy = \pm 0.005$

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3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 1080 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)

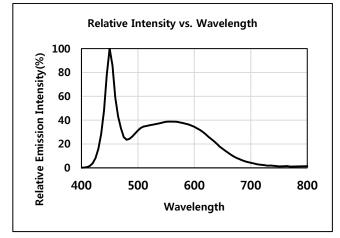




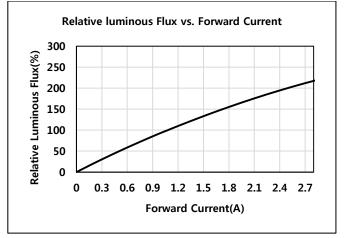
Wavelength

Wavelength

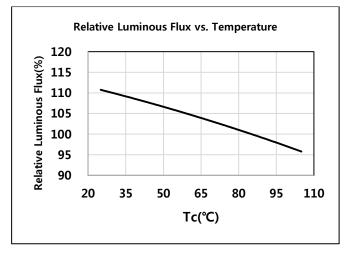
Relative Emission Intensity(%)

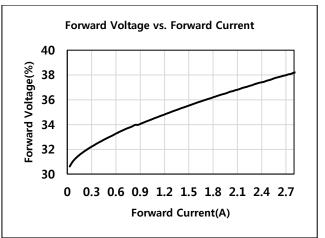


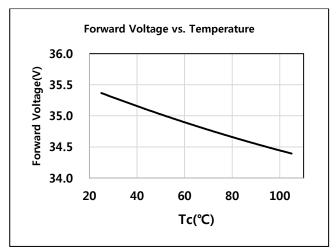
b) Forward Current Characteristics (T_J = 85 °C)



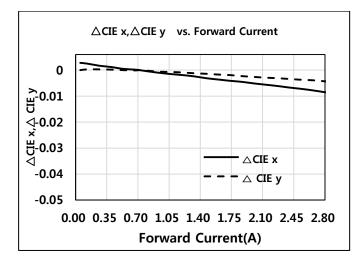
C) Temperature Characteristics (I_F = 1080mA)

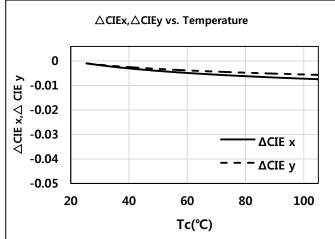




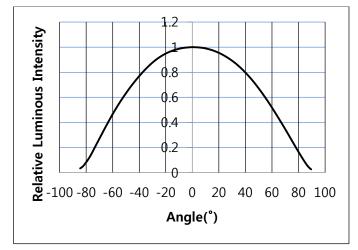


d) Color Shift Characteristics $(T_J = 25 \, {}^{\circ}C, I_F = 1080 \text{mA}, CRI80+)$

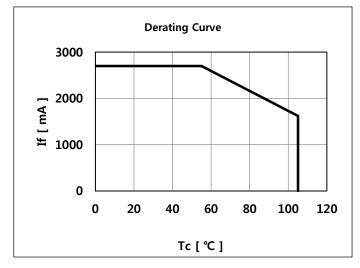




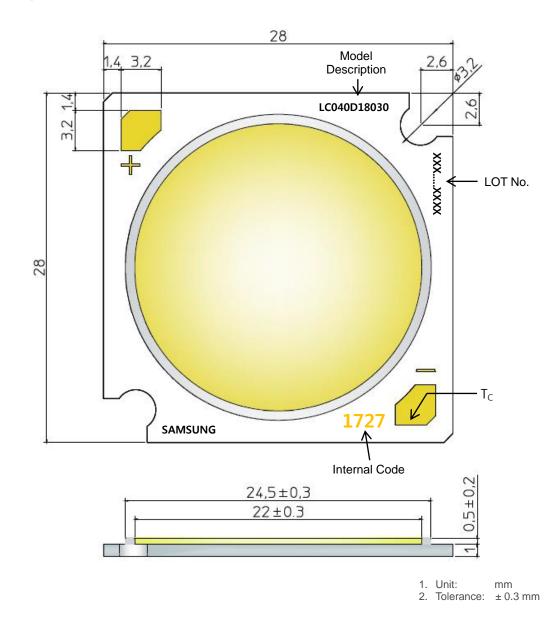
e) Beam Angle Characteristics ($I_F = 1080 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)



f) Derating Characteristics



4. Outline Drawing & Dimension



Item	Dimension	Tolerance	Unit
Length	28.0	±0.15	mm
Width	28.0	±0.15	mm
Height	1.50	±0.20	mm
Light Emitting Surface (LES) Diameter	22.0	±0.30	mm

Note: Denoted product information above is only an example (LC040D18030 : LC040D, CRI80+, 3000K)

5. Reliability Test Items & Conditions

a) Test Items

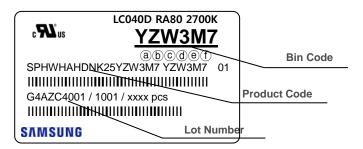
Test Item	Test Condition	Test Hour / Cycle
High Temperature Humidity Life Test	60 ℃, 90 % RH,, DC Derating, I _F	1000 h
High Temperature Life Test	85 ºC, DC Derating, I⊧	1000 h
Low Temperature Life Test	-40 °C, DC , $I_{\rm F}$ = 1900 mA	1000 h
Pulsed Operating Life Test	55 $^{\circ}\text{C},$ Pulse width 100 $\mu\text{s},$ duty cycle 3 $\%$	1000 h
High Temperature Storage	120 °C	1000 h
Low Temperature Storage	-40 °C	1000 h
Temperature Humidity Storage	60 °C, 90% RH	1000h
Thermal Cycle	-45 °C / 15 min ↔ 125 °C / 15 min temperature change in 5 min	500 cycles
Temperature Cycle On/Off Test	-40 °C / 85 °C each 20 min, 30 min transfer power on/off each 5 min, DC Derating, $I_{\rm F}$ = max	100 cycles
ESD (HBM)	R ₁ : 10 MΩ R ₂ : 1.5 kΩ C: 100 pF V: ±2 kV	5 times
ESD (MM)	R ₁ : 10 MΩ R ₂ : 0 kΩ C: 200 pF V: ±0.2 kV	5 times
Vibration Test	20 ~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency ↔ max. frequency 4 min transfer	4 times
Mechanical Shock Test	1500 g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times
Sulfur Resistance	25 °C, 75%, H2S 15 ppm	504h

b) Criteria for Judging the Damage

ltem	Symbol	Test Condition	Lin	Limit		
	Symbol	(T _c = 25 °C)	Min.	Max.		
Forward Voltage	V _F	I _F = 1080 mA	L.S.L. * 0.9	U.S.L. * 1.1		
Luminous Flux	Φ _v	I _F = 1080 mA	L.S.L * 0.7	U.S.L * 1.3		

6. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

Bin Code:

- (a) (b): Forward Voltage bin (refer to page 11)
- ©d: Chromaticity bin (refer to page 9-10)
- (e) f): Luminous Flux bin (refer to page 6)

b) Lot Number

The lot number is composed of the following characters:

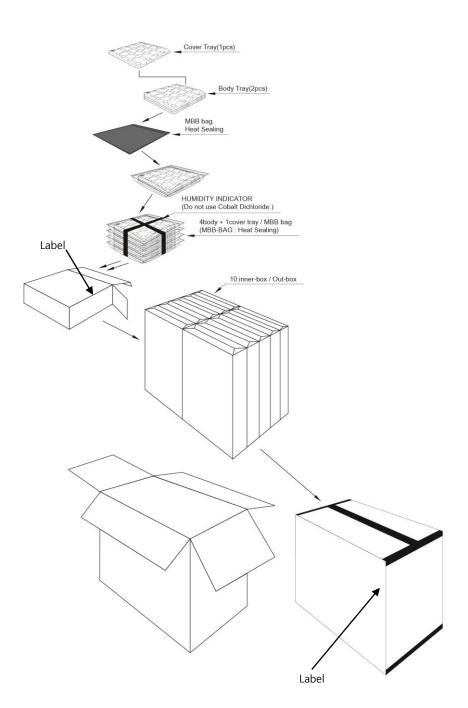


- 1 3456789 / 1abc / xxxx pcs
- (1) : Production site (S: Giheung, Korea, G: Tianjin, China)
- ② : 4 (LED)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- (4) : Year (Z: 2015, A: 2016, B: 2017...)
- (5) : Month (1~9, A, B, C)
- 6789 : Day (1~9, A, B~V)
- (a)b)c) : Product serial number (001 ~ 999)

6. Packing Structure

	Max. quantity	Dimension(mm)			
Packing material	in pcs of COB	Length	Width	Height	Tolerance
Tray	16	160	180	10	1.0
Aluminum Bag	32(2 trays)	210	241		10
Inner Box	128	230	84	260	2
Outer Box	1280	476	445	272	5

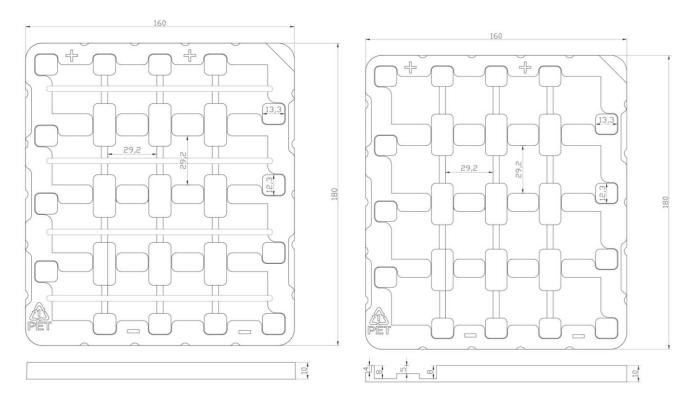
a) Packing Structure



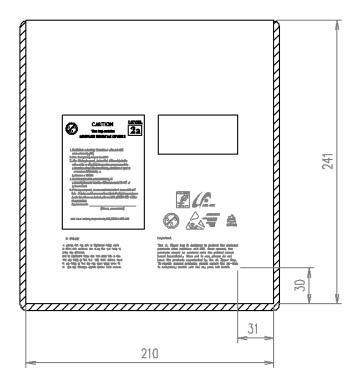
b) Tray

1 Cover

2 Body



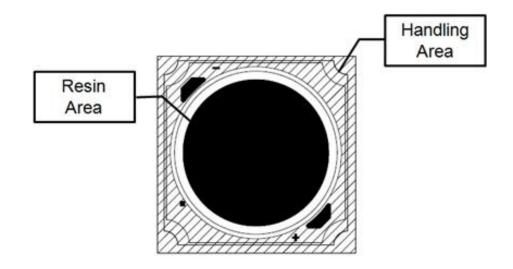
c) Aluminum Vinyl Packing Bag



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8. Precautions in Handling & Use

- This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 2) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
 b. Stored at <10 % RH
- 4) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 5) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 6) Devices must be baked for 1 hour at 60 ± 5 °C, if baking is required.
- 7) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 8) The thermal management is one of the most critical factors for the LED lighting system. Especially the LED junction temperature should not exceed the absolute maximum rating while operation of LED lighting system. For more information, please refer to Application Note 'Mechanical & Thermal Guide for COB'.
- 9) In case of driving LEDs around the minimum current level (If_min), chips might exhibit different brightness due to the variation in I-V characteristics of each one. This is normal and does not adversely affect the performance of product.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) The resin area is very sensitive, please do not handle, press, touch, rub, clean, or pick by with tweezers on it. Instead, please pick at the handling area as indicated below.



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